L Number	Hits	Search Text	DB	Time stamp
-	18	((integrated near3 circuit near3 design) or (IC near3 design) or (semiconductor near3 device)) and module and (wir$3 near3 layer) and ((horizontal and vertical and diagonal) near3 direction)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 14:37
-	1	((integrated near3 circuit near3 design) or (IC near3 design) or (semiconductor near3 device)) and module and (wir$3 near3 layer near3 (multipl$3 or plural$3)) and ((horizontal and vertical and diagonal) near3 direction)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 16:01
-	1	((integrated near3 circuit near3 design) or (IC near3 design) or (semiconductor near3 device)) and module and (wir$3 near3 layer near3 (multipl$3 or plural$3 or multilayer or (mult$3 near3 layer))) and ((horizontal and vertical and diagonal) near3 direction)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 16:06
-	15	((integrated near3 circuit near3 design) or (IC near3 design) or (semiconductor near3 device)) and module and ((mult$3 or plural$3) near3 layer) and ((horizontal and vertical and diagonal) near3 direction)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 16:31
-	17	((integrated near3 circuit) or IC or semiconductor) and module and ((mult$3 or plural$3) near3 layer) and ((horizontal and vertical and diagonal) near3 direction)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 16:39
-	1236	((integrated near3 circuit) or IC or semiconductor) and module and ((mult$3 or plural$3) near3 layer) and ((five or fifth) near3 layer) ((horizontal and vertical and diagonal) near3 direction)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 16:42
-	366	((integrated near3 circuit) or IC or semiconductor) and module and ((mult$3 or plural$3) near3 layer) and ((five or fifth) near3 layer) ((horizontal and vertical and diagonal) near3 direction) and (gridless near3 non near3 manhattan)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 16:44
-	2	((integrated near3 circuit) or IC or semiconductor) and module and ((mult$3 or plural$3) near3 layer) and ((five or fifth) near3 layer near3 metal near3 wir$3) ((horizontal and vertical and diagonal) near3 direction) and (gridless near3 non near3 manhattan) and orthogonal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/22 16:49
-	366	((integrated near3 circuit) or IC or semiconductor) and module and ((mult$3 or plural$3) near3 layer) and ((five or fifth) near3 layer) ((horizontal and vertical and diagonal) near3 direction) and (gridless near3 non near3 manhattan) and orthogonal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/23 08:23
-	0	((integrated near3 circuit) or IC or semiconductor) and module and ((mult$3 or plural$3) near3 layer) and ((five or fifth) near3 layer) and ((horizontal and vertical and diagonal) near3 direction) and (gridless near3 non near3 manhattan) and orthogonal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/23 08:24
-	15	((integrated near3 circuit) or IC or semiconductor) and module and ((mult$3 or plural$3) near3 layer) and ((five or fifth) near3 layer) and ((horizontal and vertical and diagonal) near3 direction)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/23 08:52
-	148	((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/14 10:10

-		2	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and gridless	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 15:42
-		19	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and manhattan	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/06 15:43
-		19	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and manhattan and layers	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 17:11
-		2	(manhattan same gridded) and layers	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 07:44
-		74	(manhattan and grid$4) and (metal near3 layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 07:45
-		51	(manhattan and grid$4) and (metal near3 layer) and (first near3 layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 07:46
-		36	(manhattan and grid$4) and (metal near3 layer) and (first near3 layer) and (fourth near3 layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 09:21
-		13	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and manhattan and layers and ((manhattan and grid$4) and (metal near3 layer) and (first near3 layer) and (fourth near3 layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 09:29
-		7	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and manhattan and layers and ((manhattan and grid$4) and (metal near3 layer) and (first near3 layer) and (fourth near3 layer)) and pitch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 09:06
-		9	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and manhattan and layers and pitch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 09:15
-		15	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and (manhattan or grid$4) and (metal near3 layer) and (first near3 layer) and (fourth near3 layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 09:23
-		9	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and manhattan and layers and pitch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 11:34

-	0	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and manhattan and layers and ((first near3 layer) near3 horizint$3) and ((second near3 layer) near3 vertic$3) and ((third near3 layer) near3 diagon$3) and ((fourth near3 layer) near3 diagon$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 11:45
-	0	((first near3 layer) near3 horizint$3) and ((second near3 layer) near3 vertic$3) and ((third near3 layer) near3 diagon$3) and ((fourth near3 layer) near3 diagon$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 11:38
-	0	((first near3 layer) near3 horizont$3) and ((second near3 layer) near3 vertic$3) and ((third near3 layer) near3 diagon$3) and ((fourth near3 layer) near3 diagon$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 11:38
-	16	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and manhattan and layers and (horizontal and vertical and diagonal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 17:04
-	8	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and manhattan and layers and (layer near3 (horizontal and vertical and diagonal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 12:12
-	11	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and manhattan and layers and (horizontal and vertical and diagonal) and @pd<=20030115	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 16:59
-	11	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and manhattan and layers and (horizontal and vertical and diagonal) and @pd<=20030115	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 17:04
-	11	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and manhattan and layers and (horizontal and vertical and diagonal) and @pd<=20030115	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 17:05
-	14	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and manhattan and layers and @pd<=20030115	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 09:32
-	0	simulated adj1 euclidean adj1 wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 15:30
-	0	simulated near2 euclidean near2 wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 15:30
-	0	euclidean near3 wir$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 16:22

-	0	euclidean near3 wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 16:42
-	0	(euclidean near3 (wiring or wir$3 or distance)) same (integrated near3 circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 16:43
-	1		USPAT; US-PGPUB	2003/04/21 16:49
-	0		USPAT; US-PGPUB	2003/04/21 16:56
-	0		USPAT; US-PGPUB	2003/04/21 16:55
-	0		USPAT; US-PGPUB	2003/04/21 16:55
-	0		USPAT; US-PGPUB	2003/04/21 16:55
-	0		USPAT; US-PGPUB	2003/04/21 16:55
-	1		USPAT; US-PGPUB	2003/04/21 16:55
-	0		USPAT; US-PGPUB	2003/04/21 16:55
-	1	20010009031.pn.	USPAT; US-PGPUB	2003/04/21 16:56
-	1		USPAT; US-PGPUB	2003/04/21 17:00
-	0	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and manhattan and layers and (ratio same ((first and second) near3 line))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 09:35
-	0	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and layers and (ratio same ((first and second) near3 line))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 09:35
-	17	(((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) and layers and (ratio same length)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 14:17
-	23	((((non near3 manhattan) or nonmanhattan or diagonal) near3 wiring) same ratio) and layers	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/22 14:18

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